

Claims 1 & 2 (canceled)

Claim 3 (currently amended) ~~The combination set forth in Claim 1 wherein each of said electrical contacts include longitudinally extending notches.~~ A small outline leadless package comprising:

- (a) a molding compound encapsulating discrete semiconductor devices comprising one of a solder contact bump small outline integrated circuit and a solder contact bump small outline transistor to form a package having a top, bottom, and four side surfaces;
- (b) a pair of electrical contacts each contacting a solder contact bump and extending to and flush with one of said surfaces;
- (c) each of said electrical contacts providing an exposed contact surface coplanar with said one of said surfaces and terminating at a junction between said one of said surfaces and another of said surfaces, each having longitudinally extending notches to provide mechanical attachment to the molding compound; and
- (d) the termination of said contacts occurring only at oppositely disposed package surfaces.

Claim 4 (currently amended) The combination set forth in Claim ~~1~~ 3 wherein the exposed contact surface of said electrical contacts is shaped to identify the electrical function of the encapsulated device.

Claim 5 (currently amended) The combination set forth in Claim ~~1~~ 3 wherein one of said electrical contacts is S-shaped for contacting solder bumps on a surface of said discrete semiconductor device and wherein a second electrical contact is planar and contacts solder contact bumps on an opposite side of said discrete semiconductor device.

Claims 6-7 (canceled).

Claim 8 (original) A small outline leadless package comprising:

(a) a molding compound encapsulated discrete semiconductor device comprising one of a solder contact bump small outline integrated circuit and a solder contact bump small outline transistor to form a package having a top, bottom and four side surfaces;

- (b) a pair of L-shaped electrical contacts each contacting a solder contact bump and extending to and flush with two of said package surfaces;
- (c) said electrical contacts providing an exposed contact surface coplanar with each of said two package surfaces and terminating at a junction between said two package surfaces; and
- (d) the termination of said contacts occurring only at oppositely disposed package surfaces.

Claim 9 (original) The small outline leadless package of Claim 8 wherein said discrete semiconductor device is mounted between two vertically extending legs of opposing L-shaped electrical conductors.

Claim 10 (new) A small outline leadless package comprising:

- (a) a molding compound encapsulating discrete semiconductor devices comprising one of a solder contact bump small outline integrated circuit and a solder contact bump small outline transistor to form a package having a top, bottom, and four side surfaces;

(b) a pair of electrical contacts each contacting a solder contact bump and extending to and flush with one of said surfaces;

(c) each of said electrical contacts providing an exposed contact surface coplanar with said one of said surfaces and terminating at a junction between said one of said surfaces and another of said surfaces, each of said exposed contact surfaces shaped to identify an electrical function of the encapsulated device; and

(d) the termination of said contacts occurring only at oppositely disposed package surfaces.